



## Final Product/Process Change Notification

Document #:FPCN22910X1

Issue Date:02 Sep 2020

<b>Title of Change:</b>	Update to FPCN22910X - Correction on Reliability table and Qual Vehicle.
<b>Proposed First Ship date:</b>	30 Nov 2020 or earlier if approved by customer
<b>Contact Information:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:MohdAzrul.Abdullah@onsemi.com">MohdAzrul.Abdullah@onsemi.com</a>
<b>PCN Samples Contact:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:PCN.samples@onsemi.com">PCN.samples@onsemi.com</a> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Nicky.Siu@onsemi.com">Nicky.Siu@onsemi.com</a>
<b>Type of Notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <a href="mailto:PCN.Support@onsemi.com">PCN.Support@onsemi.com</a>
<b>Marking of Parts/ Traceability of Change:</b>	Affected products will be identified with marking code from new plant
<b>Change Category:</b>	Test Change, Assembly Change
<b>Change Sub-Category(s):</b>	Datasheet/Product Doc change, Material Change

**Sites Affected:**

ON Semiconductor Sites	External Foundry/Subcon Sites
ON Semiconductor Seremban, Malaysia	Chipbond Technology Hsinchu, Taiwan
	SPEL Semiconductor Limited

**Description and Purpose:**

This Update Notification is issued to provide update on the Reliability data for qualification vehicle (QV) devices in FPCN22910X issued in 08, August 2020.

**FPCN22910X** was issued the migration qualification of ON Semiconductor Seremban, Malaysia from SPEL Semiconductor Limited, India and Chipbond Technology Hsinchu, Taiwan.

Below is detail of change.

	Before Change Description	After Change Description
<b>Bond Wire</b>	0.9 MIL AU	0.8 MIL AU
<b>Mold Compound</b>	MC G770HCD HF	MC SUMITOMO G760
<b>Back Metallization Site</b>	Chipbond Technology Hsinchu, Taiwan	ON Semiconductor, Malaysia
<b>Assembly Site</b>	SPEL, India	ON Semiconductor, Malaysia
<b>Test Site</b>	SPEL, India	ON Semiconductor, Malaysia

No package dimension change and no product performance change.

The datasheet is updated with notes that the capacitance condition is guaranteed by design.

**Reliability Data Summary:**QV DEVICE NAME : CM1624-08DERMS: S58877PACKAGE: UDFN16 3.3x1.35

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=125°C, 80% max rated V	1008hrs	0/252
H3TRB	JESD22-A101	85°C, 85% RH, biased	1008hrs	0/252
HTSL	JESD22-A103	Ta=150°C	1008hrs	0/252
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000cyc	0/252
TC	JESD22-A104	Ta= -65°C to +150°C, mount on board	1000cyc	0/252
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/252
PC	J-STD-020 JESD-A113	MSL1 @ 260 °C		0/1008
RSH	JESD22- B106	Ta = 265C, 10 sec		0/90
SD	JSTD002	Ta = 245C, 5 sec		0/45

**Electrical Characteristics Summary:**

Electrical characteristics are not impacted

**List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
CM1624-08DE	CM1624-08DE
CM1693-04DE	CM1624-08DE